

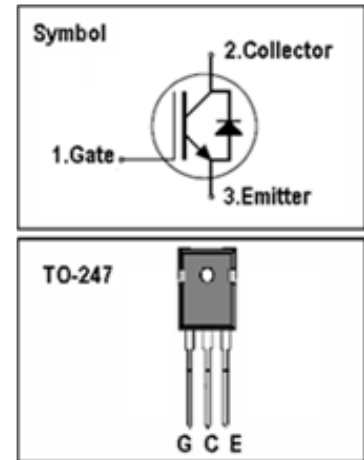
## IGBT

### Features

- 1200V,25A
- $V_{CE(sat)(typ.)}=1.66V@V_{GE}=15V,I_C=25A$
- High speed switching
- Higher system efficiency
- Soft current turn-off waveforms
- Square RBSOA

### General Description

JIAEN Trench IGBTs offer lower losses and higher energy efficiency for application such as Motor control, general inverter and other soft switching applications.



### Absolute Maximum Ratings

Symbol	Parameter	Value	Units
$V_{CES}$	Collector-Emitter Voltage	1200	V
$V_{GES}$	Gate-Emitter Voltage	$\pm 30$	V
$I_C$	Continuous Collector Current ( $T_C=25^\circ C$ )	50	A
	Continuous Collector Current ( $T_C=100^\circ C$ )	25	A
$I_{CM}$	Pulsed Collector Current (Note 1)	75	A
$I_F$	Diode Continuous Forward Current ( $T_C=100^\circ C$ )	25	A
$I_{FM}$	Diode Maximum Forward Current (Note 1)	75	A
$t_{sc}$	Short Circuit Withstand Time	10	us
$P_D$	Maximum Power Dissipation ( $T_C=25^\circ C$ )	250	W
$T_J$	Operating Junction Temperature Range	-55 to +175	$^\circ C$
$T_{STG}$	Storage Temperature Range	-55 to +175	$^\circ C$

### Thermal Characteristics

Symbol	Parameter	Max.	Units
$R_{th\ j-c}$	Thermal Resistance, Junction to case for IGBT	0.45	$^\circ C/W$
$R_{th\ j-c}$	Thermal Resistance, Junction to case for Diode	0.3	$^\circ C/W$
$R_{th\ j-a}$	Thermal Resistance, Junction to Ambient	40	$^\circ C/W$

**Electrical Characteristics** ( $T_C=25^\circ\text{C}$  unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$BV_{CES}$	Collector-Emitter Breakdown Voltage	$V_{GE}=0V, I_C=1mA$	1200	-	-	V
$I_{CES}$	Collector-Emitter Leakage Current	$V_{CE}=1200V, V_{GE}=0V$	-	-	1	$\mu A$
$I_{GES}$	Gate Leakage Current, Forward	$V_{GE}=\pm 30V, V_{CE}=0V$	-	-	$\pm 200$	nA
$V_{GE(th)}$	Gate Threshold Voltage	$V_{GE}=V_{CE}, I_C=1mA$	5.6	-	8.0	V
$V_{CE(sat)}$	Collector-Emitter Saturation Voltage	$V_{GE}=15V, I_C=25A$	-	1.66	2.1	V
$Q_g$	Total Gate Charge	$V_{CC}=600V$ $V_{GE}=15V$ $I_C=25A$	-	106		nC
$Q_{ge}$	Gate-Emitter Charge		-	26.2		nC
$Q_{gc}$	Gate-Collector Charge		-	48		nC
$t_{d(on)}$	Turn-on Delay Time	$V_{CC}=600V$ $V_{GE}=15V$ $I_C=25A$ $R_G=4\Omega$ Inductive Load $T_C=25^\circ\text{C}$	-	24.3	-	ns
$t_r$	Turn-on Rise Time		-	7.36	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	126	-	ns
$t_f$	Turn-off Fall Time		-	125	-	ns
$E_{on}$	Turn-on Switching Loss		-	1.37	-	mJ
$E_{off}$	Turn-off Switching Loss		-	1.13	-	mJ
$E_{ts}$	Total Switching Loss		-	2.5	-	mJ
$C_{ies}$	Input Capacitance	$V_{CE}=25V$	-	2600	-	pF
$C_{oes}$	Output Capacitance	$V_{GE}=0V$	-	85	-	pF
$C_{res}$	Reverse Transfer Capacitance	$f=1MHz$	-	20	-	pF

**Electrical Characteristics of Diode** ( $T_C=25^\circ\text{C}$  unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$V_F$	Diode Forward Voltage	$I_F=25A$	-	1.9	2.8	V
$t_{rr}$	Diode Reverse Recovery Time	$V_{CE}=600V$	-	357		ns
$I_{rr}$	Diode peak Reverse Recovery Current	$I_F=25A$	-	7.95		A
$Q_{rr}$	Diode Reverse Recovery Charge	$dI_F/dt=200A/\mu s$	-	1550		nC

**Notes:**

1. Repetitive Rating: Pulse width limited by maximum junction temperature

## Typical Performance Characteristics

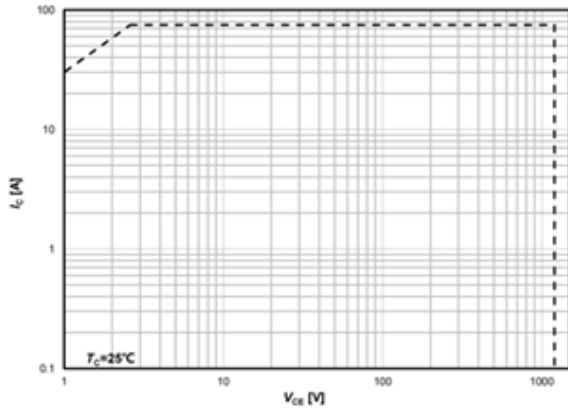


Figure 1. Forward bias safe operating area

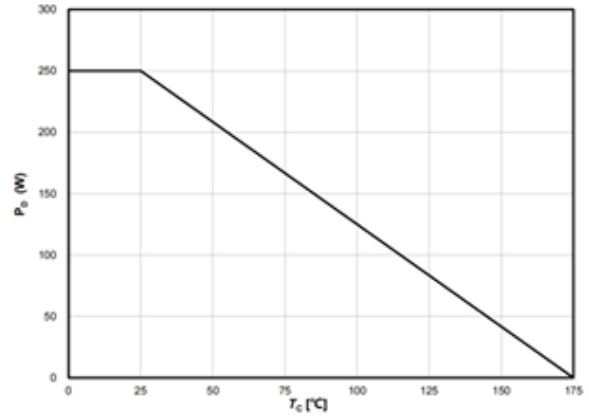


Figure 2. Power dissipation as a function of case temperature

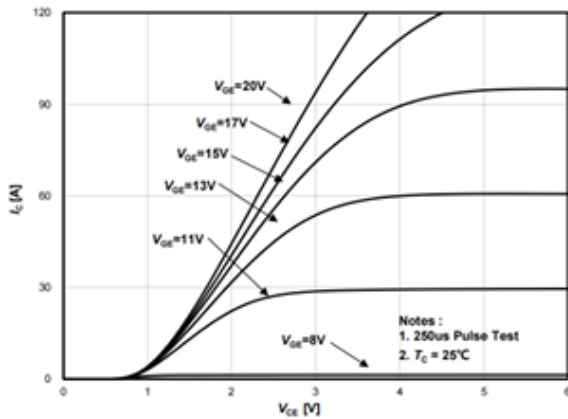


Figure 3. Typical output characteristic(25°C)

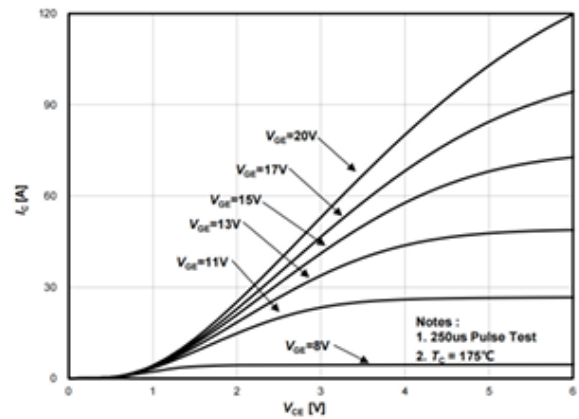


Figure 4. Typical output characteristic(175°C)

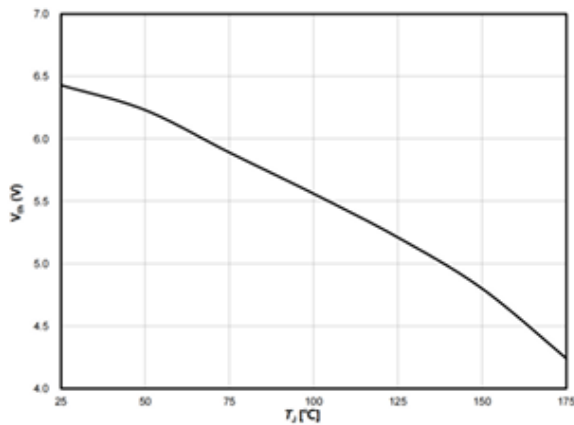


Figure 5. Gate-emitter threshold voltage as a function of junction temperature

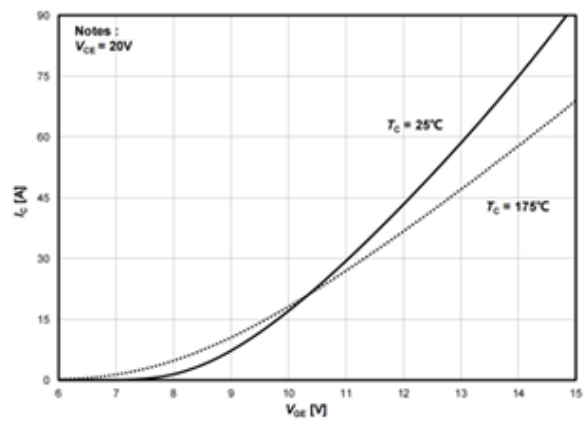


Figure 6. Typical transfer characteristic

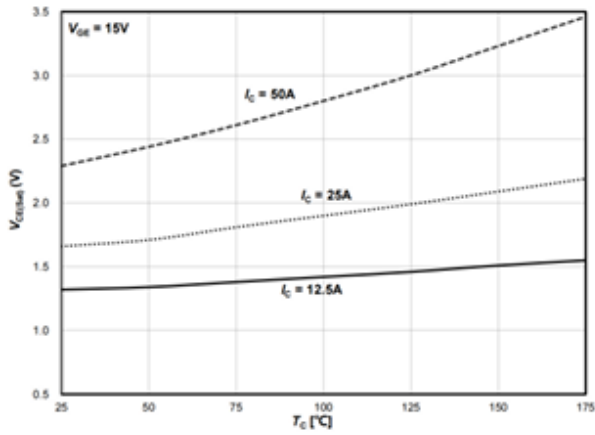


Figure 7. Typical collector-emitter saturation voltage as a function of junction temperature

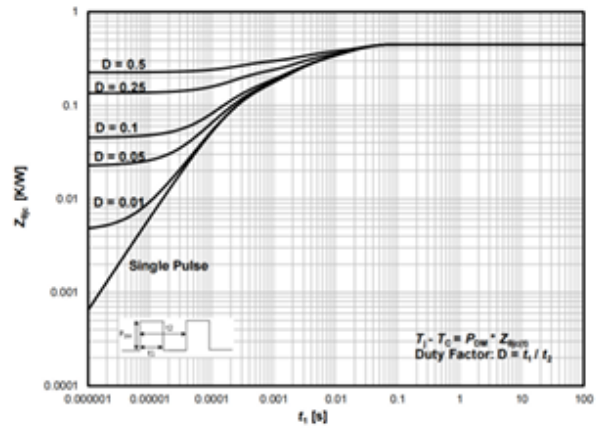


Figure 8. IGBT transient thermal impedance

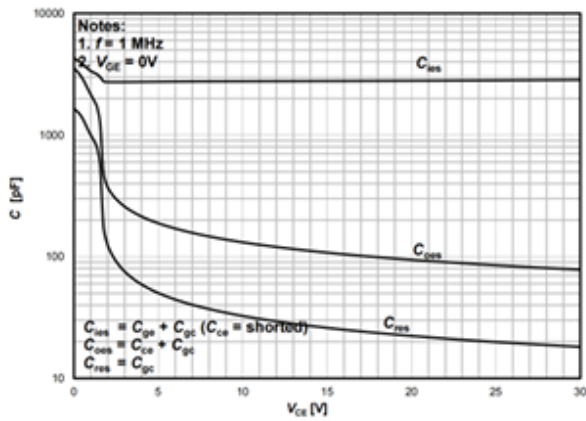


Figure 9. Typical capacitance as a function of collector-emitter voltage

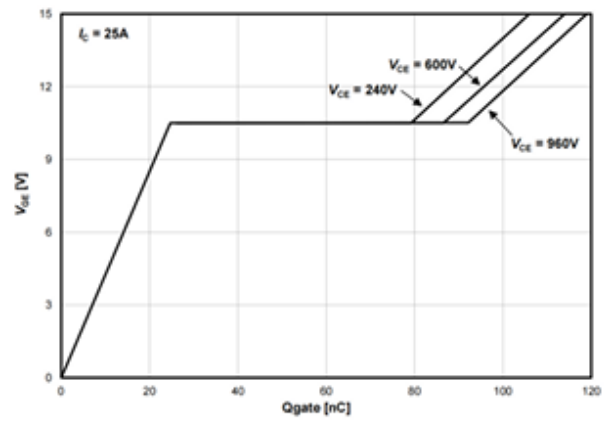


Figure 10. Typical gate charge

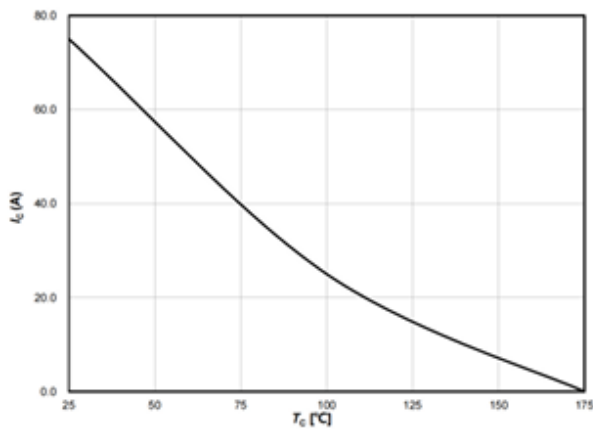


Figure 11. Collector current as a function of case temperature

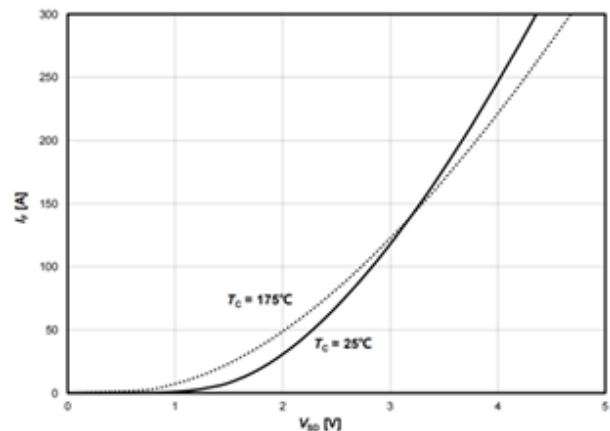


Figure 12. Typical diode forward current as a function of forward voltage

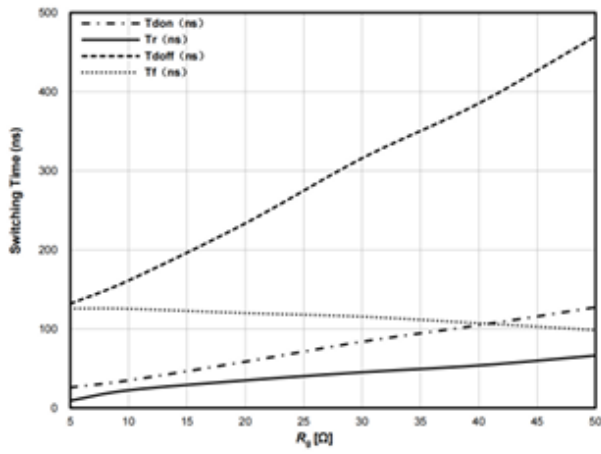


Figure 13. Typical switching times as a function of gate resistance

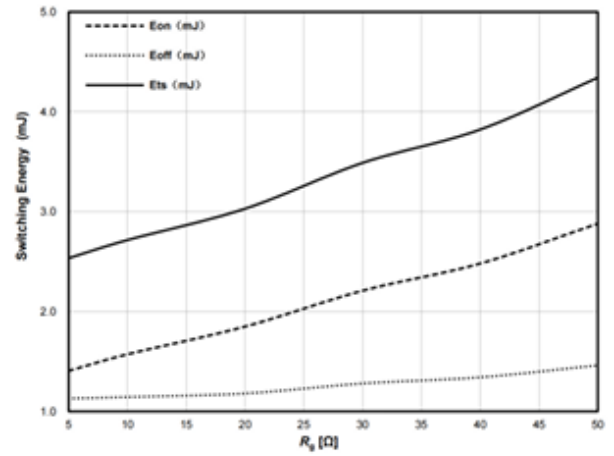


Figure 14. Typical switching energy losses as a function of gate resistance

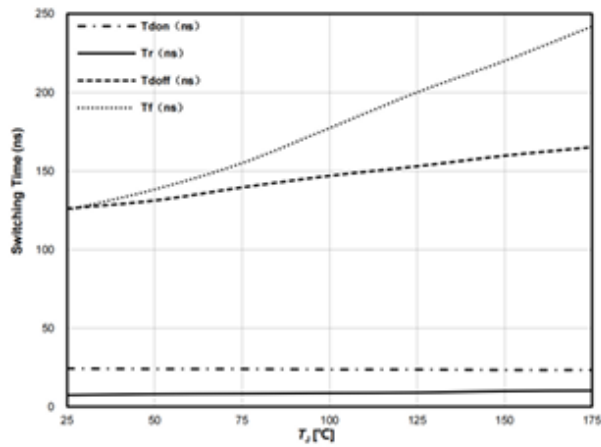


Figure 15. Typical switching times as a function of junction temperature

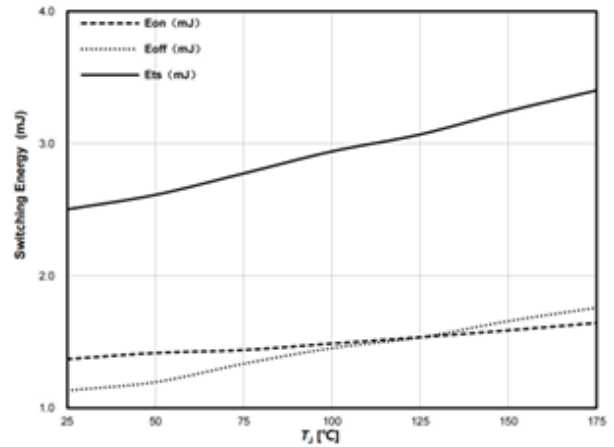


Figure 16. Typical switching energy losses as a function of junction temperature

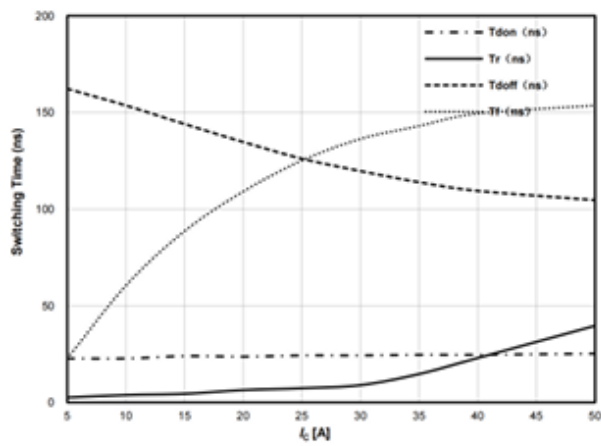


Figure 17. Typical switching times as a function of collector current

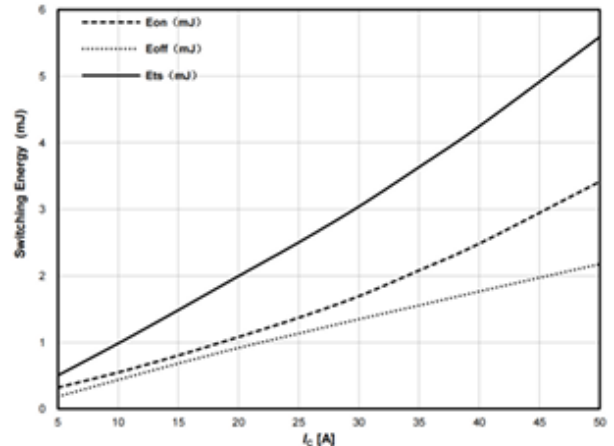


Figure 18. Typical switching energy losses as a function of collector current

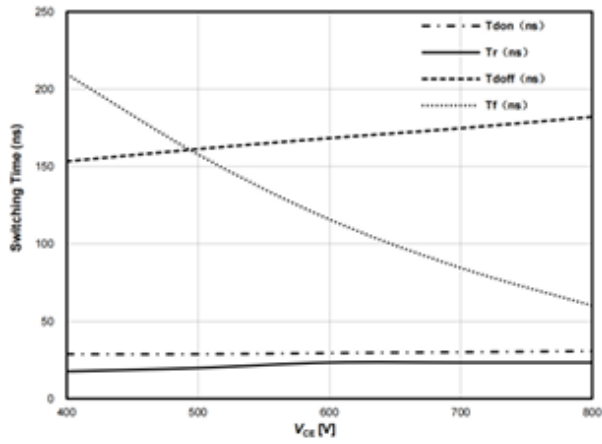


Figure 19. Typical switching times as a function of collector emitter voltage

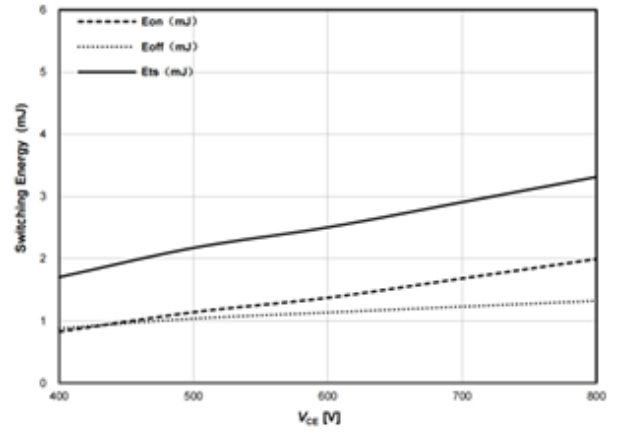
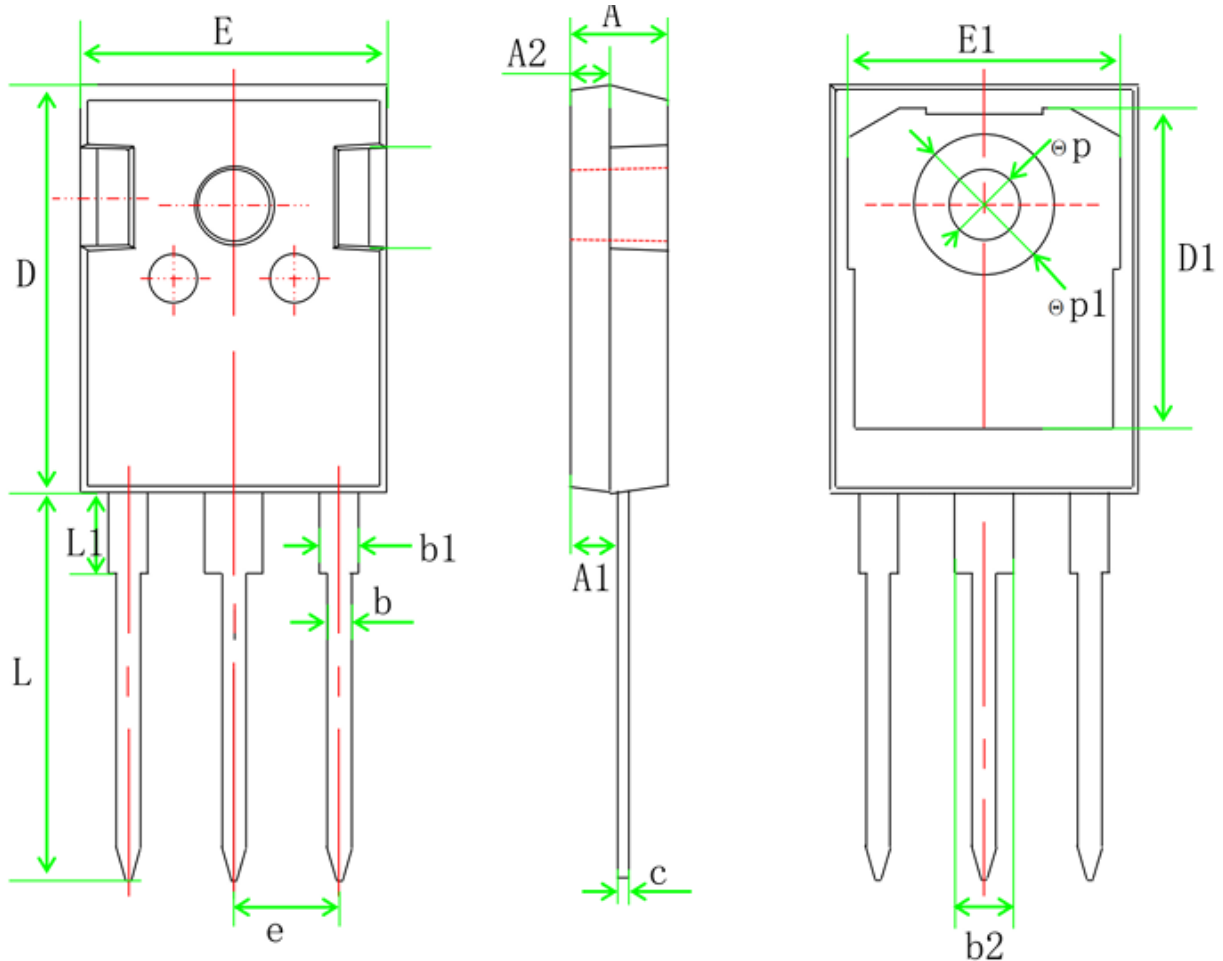


Figure 20. Typical switching energy losses as a function of collector emitter voltage

**TO-247 PACKAGE OUTLINE**



SYMBOL	Mechanical Dimensions/mm			SYMBOL	Mechanical Dimensions/mm		
	MIN	NOM	MAX		MIN	NOM	MAX
A	4.80	5.00	5.20	D	20.70	21.00	21.30
A1	2.21	2.41	2.61	D1	16.25	16.55	16.85
A2	1.85	2.00	2.15	E	15.50	15.80	16.10
b	1.10	1.20	1.36	E1	13.00	13.30	13.60
b1	1.90	2.00	2.21	L	19.42	19.92	20.42
b2	2.85	3.00	3.21	L1	4.03	4.13	4.43
c	0.45	0.60	0.75	$\varnothing p$	3.45	3.60	3.75
e	5.29	5.44	5.59	$\varnothing p1$			7.4

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